



**TARGET THICKNESS: 0.125"**  
**NUMBER OF LAYERS: 08**

# MULTILAYER PCB CONSTRUCTION SHEET

If there are max thickness requirements beyond +/- .10% overall - non-standard construction should be ordered and notes added.

<b>8 Layer StackUp (0.125") L08-125-1oz1oz</b>		<b>Thickness (inches)</b>
<b>Layer 1</b>	<b>1 oz foil plated to approximate* thickness 0.0024"</b>	0.0024
Prepreg	Bonding ply (2x2116) Average Dielectric Constant 4.5	0.0084
<b>Layer 2</b>	<b>1 oz foil thickness</b>	0.0014
Core	Laminate Core Dielectric Constant 4.5 (+/- 0.10)	0.028
<b>Layer 3</b>	<b>1 oz foil thickness</b>	0.0014
Prepreg	Bonding ply (1x2116, 1x1080) Average Dielectric Constant 4.5	0.0064
<b>Layer 4</b>	<b>1 oz foil thickness</b>	0.0014
Core	Laminate Core Dielectric Constant 4.5 (+/- 0.10)	0.028
<b>Layer 5</b>	<b>1 oz foil thickness</b>	0.0014
Prepreg	Bonding ply (1x2116, 1x1080) Average Dielectric Constant 4.5	0.0064
<b>Layer 6</b>	<b>1 oz foil thickness</b>	0.0014
Core	Laminate Core Dielectric Constant 4.5 (+/- 0.10)	0.028
<b>Layer 7</b>	<b>1 oz foil thickness</b>	0.0014
Prepreg	Bonding ply (2x2116) Average Dielectric Constant 4.5	0.0084
<b>Layer 8</b>	<b>1 oz foil plated to approximate* thickness 0.0024"</b>	0.0024
"Thickness does not include soldermask or surface finish"		<b>0.1268</b>

## NOTES: